



FOR IMMEDIATE RELEASE

**MAJOR AUSTRIAN SEMICONDUCTOR MANUFACTURER BROADENS MEMS AND DISPLAY
DEVICE PACKAGING CAPACITY WITH INSTALLATION OF FOURTH IQ ALIGNER
FROM EV GROUP**

ST. FLORIAN, Austria, Oct. 9, 2007—EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced the successful installation of its fourth IQ Aligner System for packaging applications at a major semiconductor manufacturing facility in Austria. This purchase further strengthens the customer's capacity for wafer-level packaging of MEMS and display devices, while underscoring the enabling, cost-effective nature of the IQ Aligner's core technology.

According to the chipmaker's facility production manager, "Increased throughput and reduced cost of ownership (CoO) for products formerly processed on the company's steppers made the IQ Aligner the best choice for a reliable and precise production tool." Allowing for maximum tool flexibility, the customer's IQ Aligners are continuously updated with new process capabilities. The first IQ Aligner originally started with standard wafer handling and was upgraded in the field to thin-wafer handling capabilities (wafer thickness down to 70 microns on 150-mm substrates), which was already included in the order for the following systems. The latest upgrade included special infrared (IR) capabilities for fully automated alignment of inner substrate-alignment keys on temporary bonded silicon wafer pairs.

The electronics-device manufacturing industry is increasingly grasping the potential for minimizing production costs by transitioning the processing of devices from steppers to proximity mask aligners. When evaluated head-to-head against competitive mask-alignment systems, the IQ Aligner has benefited from some key advantages, most notably its exclusive, contactless substrate wedge compensation technology, which eliminates all physical contact between wafer and mask for proximity exposure modes, and its new NanoAlign[®] capability for improved automatic alignment accuracy and reliability.

"Receiving the fourth repeat order for our IQ Aligner from this leading semiconductor manufacturer directly reflects the high-volume capabilities of the system," said Alois Malzer, product manager for mask aligners at EVG. "In addition, EVG achieved installation of the fourth system in the southern part of Austria within seven working days—from initial hook up to production release, illustrating the strength of EVG's support team to fully satisfy or exceed customer expectations."

Further information regarding EVG's IQ Aligner, as well as its full portfolio of leading-edge wafer-bonding and lithography equipment, will be available during SEMICON Europa, Oct. 9-11, 2007 at the Stuttgart Trade Fair Centre in Stuttgart, Germany. Editors and analysts interested in learning more about the company and its products are invited to visit EVG's booth #912 (Hall 1).

About EV Group (EVG)

Founded in 1980, EV Group is a global supplier of wafer bonders, aligners, photoresist coaters, cleaners and inspection systems for semiconductor, MEMS and emerging nanotechnology markets. EVG holds the dominant share of the market for wafer bonding equipment and is a leader in lithography for advanced packaging, MEMS and nanoimprint lithography (NIL).

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The company's unique Triple “i” approach (INVENT - INNOVATE - IMPLEMENT) is supported by a vertical infrastructure, allowing EV Group to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. Headquartered in St. Florian, Austria, EV Group operates via a global customer support network, with subsidiaries in Tempe, Arizona; Albany, New York; Yokohama and Fukuoka, Japan; and Chung-Li, Taiwan. For more information, visit www.EVGroup.com and our EVG-TShop “Click, Stop – the new way to shop,” www.EVGShop.com

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